

L Number	Hits	Search Text	DB	Time stamp
1	114083	inductance or inductor\$1	USPAT; US-PGPUB; JPO	2004/09/13 12:31
2	1093836	wire\$1 or wiring\$1	USPAT; US-PGPUB; JPO	2004/09/13 12:31
3	1068990	die\$1 or chip\$1 or ic or (integrated adj circuit\$1)	USPAT; US-PGPUB; JPO	2004/09/13 12:32
4	504223	packag\$3	USPAT; US-PGPUB; JPO	2004/09/13 12:32
5	1008178	resin	USPAT; US-PGPUB; JPO	2004/09/13 12:32
6	17968	(inductance or inductor\$1) same (wire\$1 or wiring\$1)	USPAT; US-PGPUB; JPO	2004/09/13 12:32
7	35031	leadframe\$1or (lead adj frame\$1)	USPAT; US-PGPUB; JPO	2004/09/13 12:33
8	920312	bond\$3	USPAT; US-PGPUB; JPO	2004/09/13 12:33
9	125358	(wire\$1 or wiring\$1) same (die\$1 or chip\$1 or ic or (integrated adj circuit\$1))	USPAT; US-PGPUB; JPO	2004/09/13 12:34
10	13391	(leadframe\$1or (lead adj frame\$1)) and ((wire\$1 or wiring\$1) same (die\$1 or chip\$1 or ic or (integrated adj circuit\$1)))	USPAT; US-PGPUB; JPO	2004/09/13 12:34
11	12002	bond\$3 and ((leadframe\$1or (lead adj frame\$1)) and ((wire\$1 or wiring\$1) same (die\$1 or chip\$1 or ic or (integrated adj circuit\$1))))	USPAT; US-PGPUB; JPO	2004/09/13 12:34
12	1322	(inductance or inductor\$1) and (bond\$3 and ((leadframe\$1or (lead adj frame\$1)) and ((wire\$1 or wiring\$1) same (die\$1 or chip\$1 or ic or (integrated adj circuit\$1))))	USPAT; US-PGPUB; JPO	2004/09/13 12:34
13	505	((inductance or inductor\$1) and (bond\$3 and ((leadframe\$1or (lead adj frame\$1)) and ((wire\$1 or wiring\$1) same (die\$1 or chip\$1 or ic or (integrated adj circuit\$1)))))) and resin	USPAT; US-PGPUB; JPO	2004/09/13 12:35